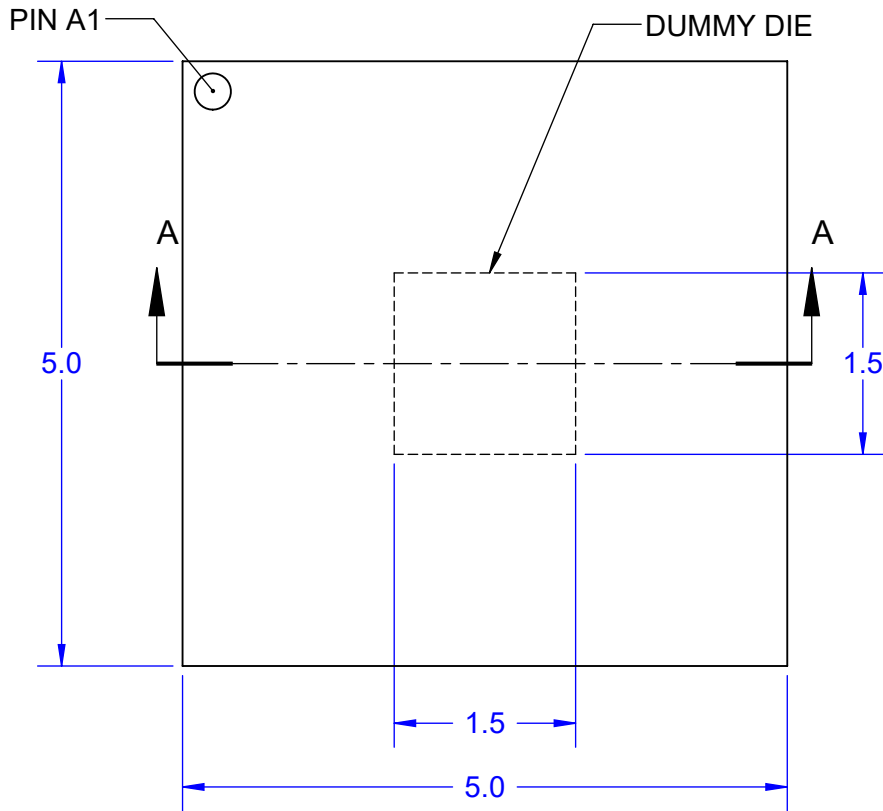
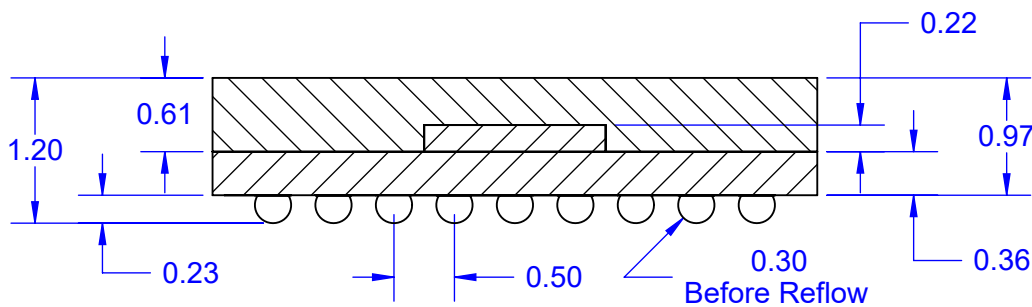
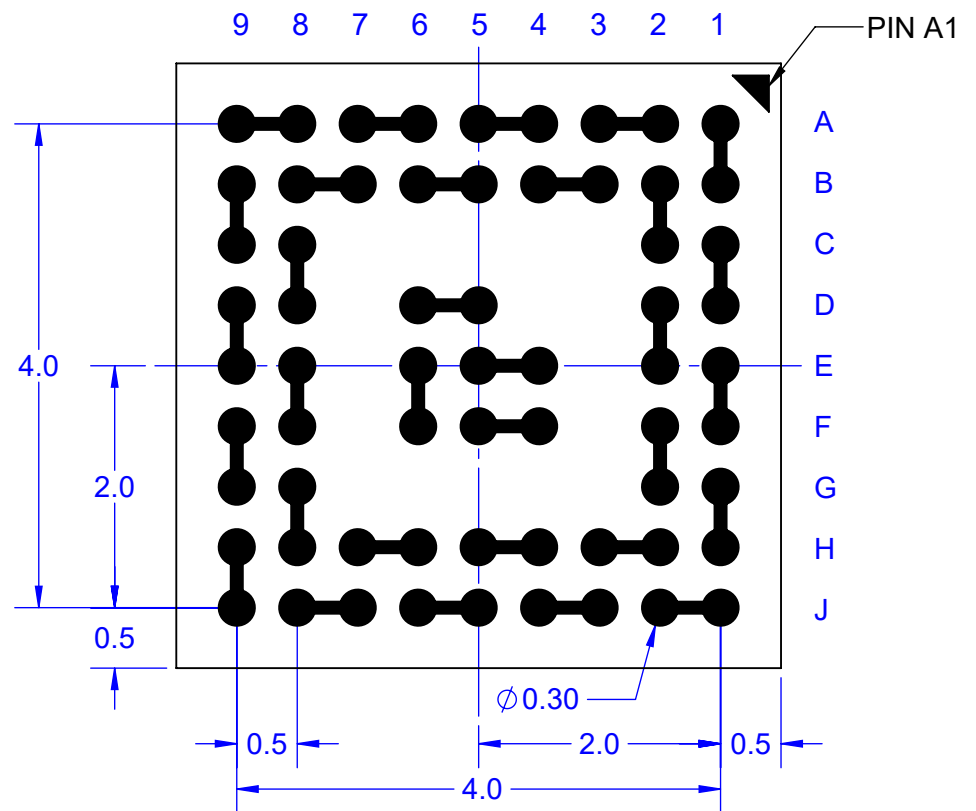


TOP VIEW



BALL VIEW



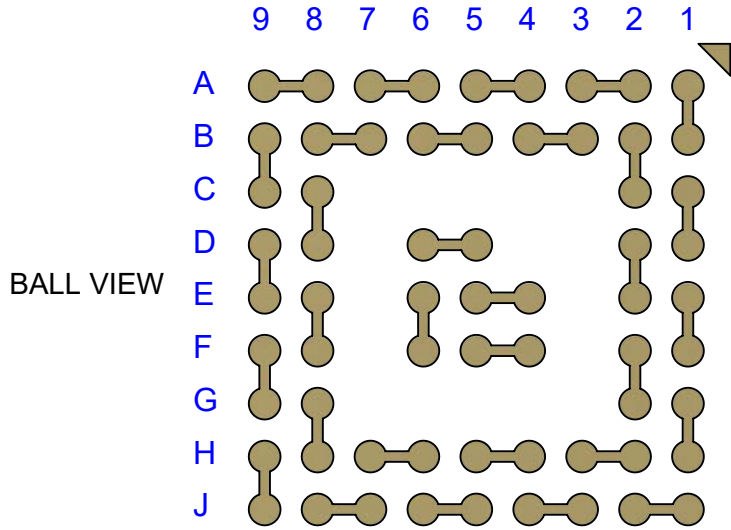
SECTION A-A

Notes: (Unless Otherwise Specified).

- 1) ALL DIMENSIONS: MM.
- 2) SOLDER BALL ALLOY: SEE PART NUMBER TABLE.
- 3) BALL DIAMETER (BEFORE REFLOW): 0.30mm.
- 4) SOLDER MASK DEFINED PAD OPENING: 0.254mm [10 MIL].
- 5) PAD Cu DIAMETER: 0.30mm [12 MIL].
- 6) SUBSTRATE MATERIAL: BT.
- 7) MSL-3 RECOMMEND BAKING 24 HOURS @ 125C TO REMOVE MOISTURE PRIOR TO SOLDERING TO PC BOARD.

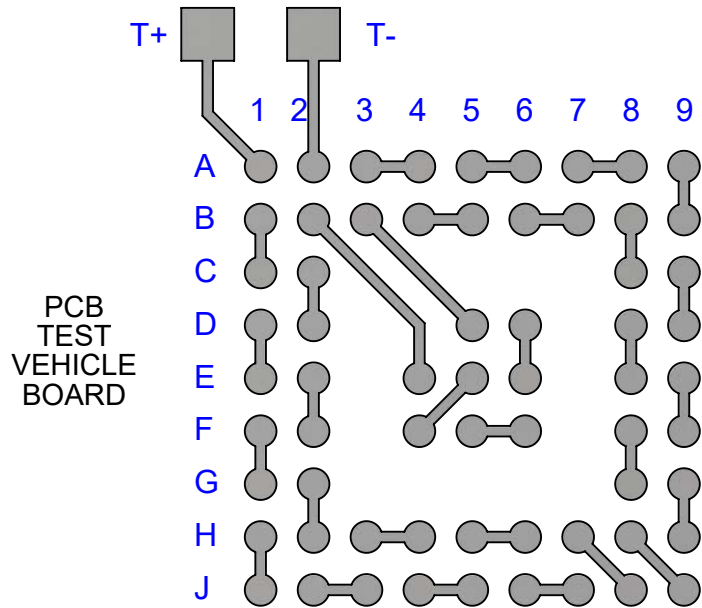
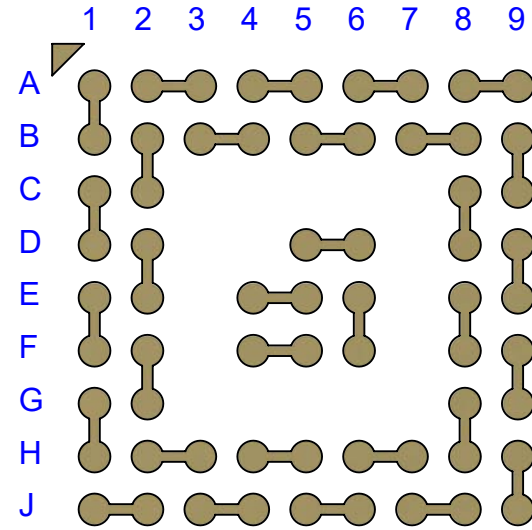
PART NUMBER TABLE				
PART NUMER	BALL ALLOY	Pb-FREE	RoHS	Si DIE
BGA64T.5C-DC092D	Sn96.5/Ag3.0/Cu0.5	YES	YES	YES
BGA64T.5-DC092D	Sn63/Pb37	NO	NO	YES

APPROVALS	DATE	TopLine®			
DRAWN T.Au	12/22/2024				
ENG M. Hart	12/22/2024	TITLE BGA64T.5-DC092D DAISY CHAIN DUMMY			
MFG		SCALE 15:1	SIZE A	DRAWING NO. 550921	REV A
REVISD		DO NOT SCALE DRAWING			SHEET 1 OF 4



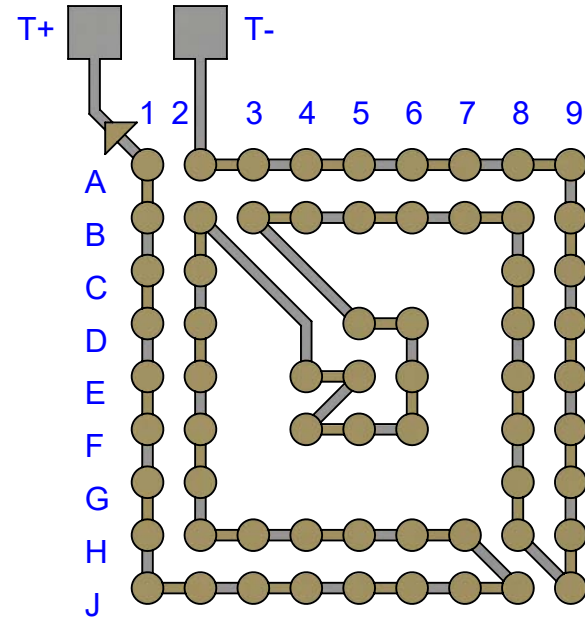
BALL VIEW

BOTTOM SIDE
(TOP X-RAY VIEW)



PCB
TEST
VEHICLE
BOARD

AFTER MOUNTING
TO TEST BOARD
(TOP X-RAY VIEW)

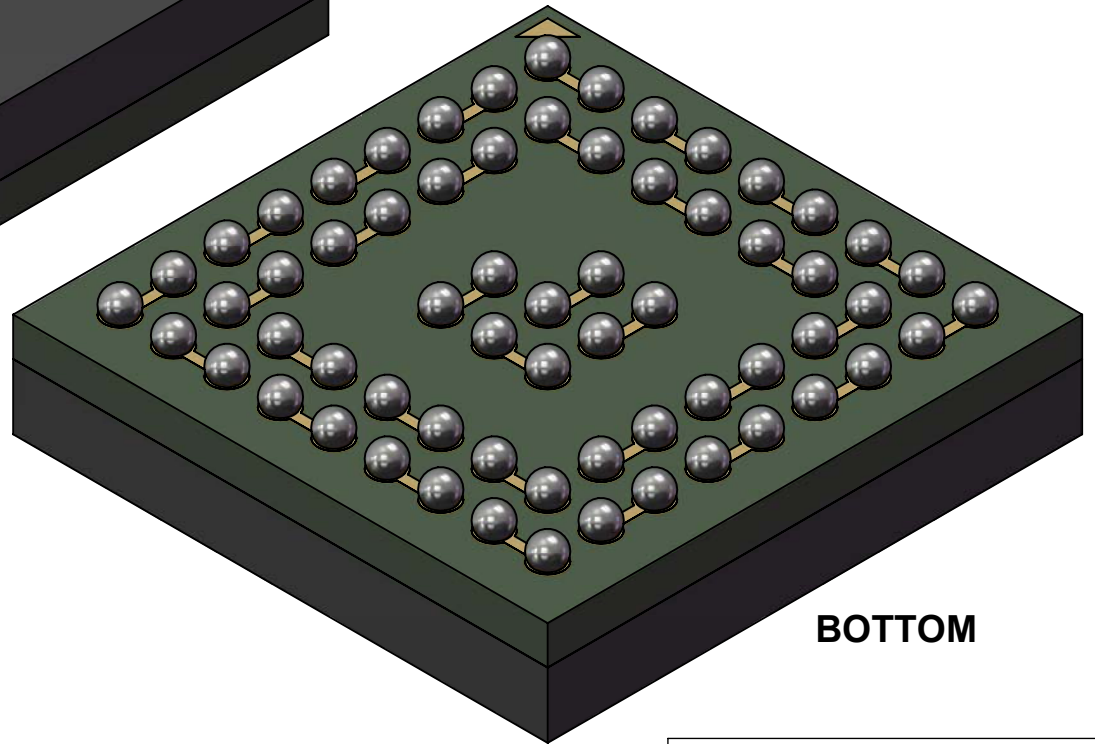
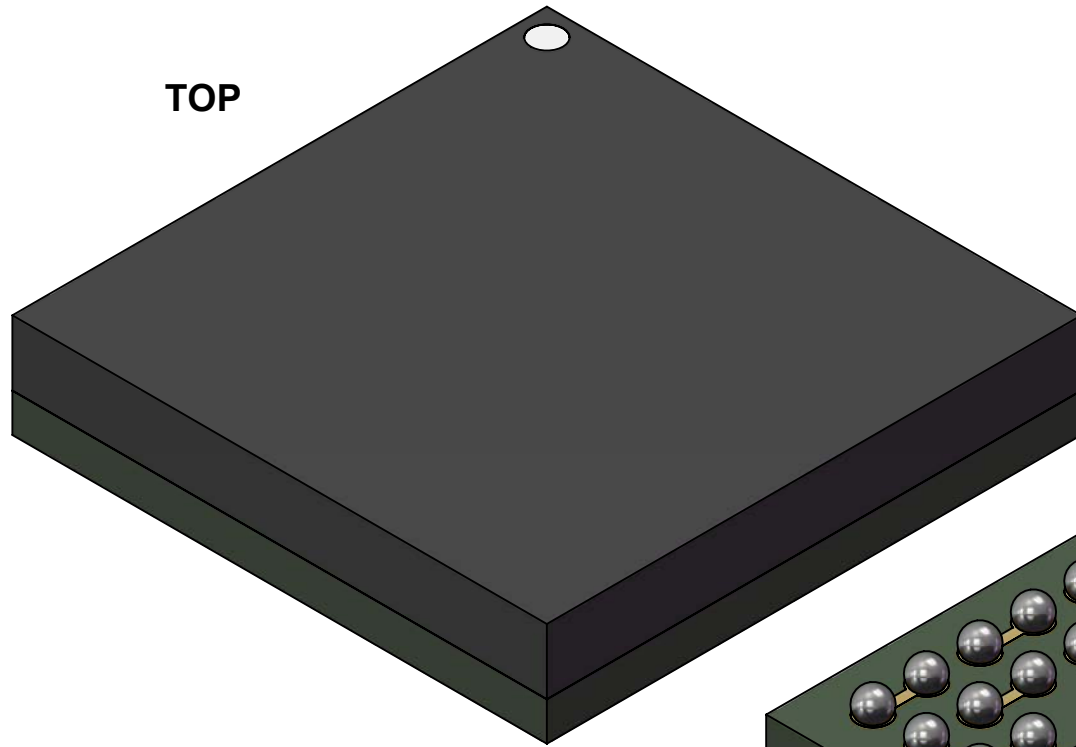


- Notes:
- 1) PCB BOARD DIMENSIONS ARE PRESENTED ONLY AS A GUIDELINE. DESIGNERS SHOULD USE THEIR OWN EXPERIENCE WHEN DESIGNING PCB.
 - 2) PCB Cu BALL PAD DIAMETER 0.30mm [12 MIL].
 - 3) SMD (SOLDER MASK DEFINED) PAD OPENING 0.254mm [10 MIL].

TopLine®			
TITLE		BGA64T.5-DC092D DAISY CHAIN DUMMY	
SCALE	SIZE	DRAWING NO.	REV
14:1	A	550921	A
DO NOT SCALE DRAWING			SHEET 2 OF 4

MODELS

TOP



BOTTOM

TopLine[®]

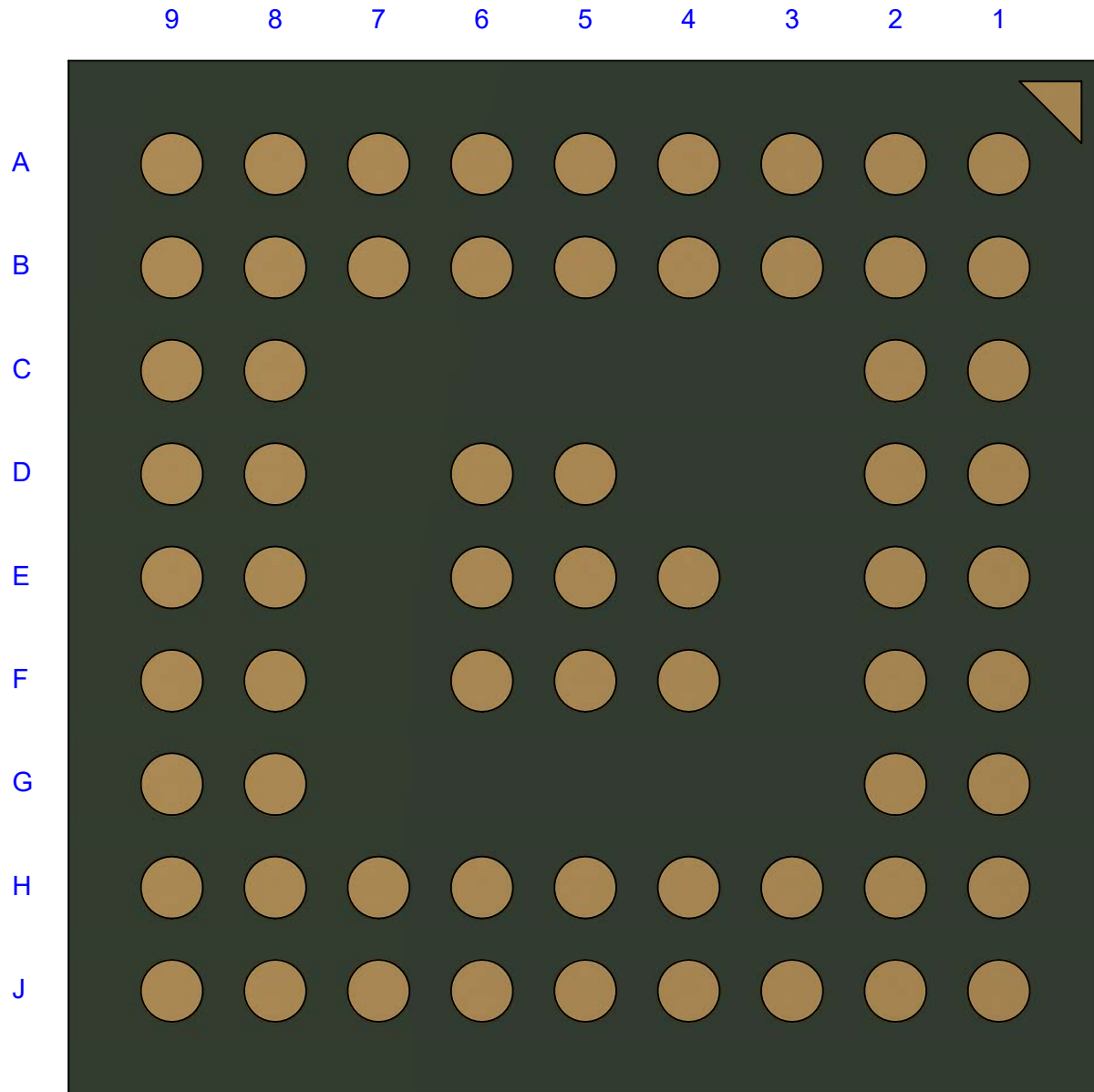
TITLE BGA64T.5-DC092D
DAISY CHAIN DUMMY

SCALE 20:1	SIZE A	DRAWING NO. 550921	REV A
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DO NOT SCALE DRAWING

SHEET 3 OF 4

BOTTOM SOLDER MASK RIGHT READING



TopLine[®]			
TITLE		BGA64T.5-DC092D DAISY CHAIN DUMMY	
SCALE	SIZE	DRAWING NO.	REV
30:1	A	550921	A
DO NOT SCALE DRAWING			SHEET 4 OF 4